



EV085432809 GW 06/04/03
#39

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/148,723
Filing Date September 3, 1998
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner A.D. Tugbang
Attorney's Docket No. MI22-981
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate

**RESPONSE TO FEBRUARY 24, 2003 NOTICE OF ALLOWANCE
TO ACCOMPANY REQUEST FOR CONTINUED EXAMINATION**

To: Box RCE
Assistant Commissioner for Patents
Washington, D.C. 20231

From: D. Brent Kenady
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Sir:

Please enter the following prior to examining the above identified application:

REMARKS

Claims 1-3, 6, 8, 11, 13, 20, 22, 23, 26, 27, 30, 31, 36, 37, 45 and 48-53 were indicated to be allowable in the parent application. This request for continued examination is being submitted out of an overabundance of caution to have the allowed claims considered in light of additional prior art. Such art is